



Flanged Termination 60 Watts, 50Ω



General Specifications

| | |
|--------------------------|------------------------------------|
| Resistive Element | Thick film |
| Substrate | Beryllium oxide ceramic |
| Cover | Alumina Ceramic |
| Mounting flange | Copper, nickel plated per QQ-N-290 |
| Leads | 99% pure silver (.005" thick) |

Electrical Specifications

| | |
|--------------------------|--------------------|
| Resistance Range: | 50 ohms, $\pm 5\%$ |
| Frequency Range; | DC – 6.0 GHz |
| Power: | 60 Watts |
| VSWR: | 1.25:1 to 6.0 GHz |

Note: Tolerance is $\pm 0.010"$, unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. Operating temperature is -55°C to 150°C (see chart for derating temperatures).

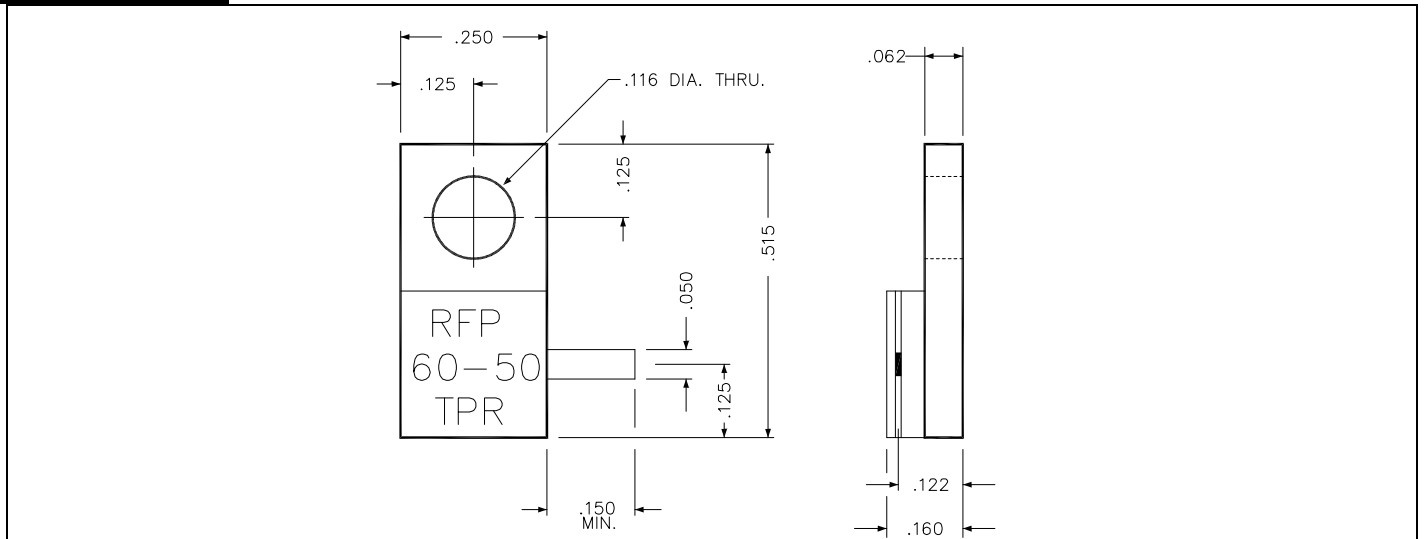
All dimensions in inches.

Specifications subject to change with out notice.

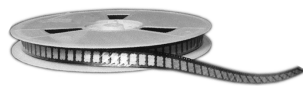
Features:

- DC –6.0 GHz
- 60 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

Outline Drawing

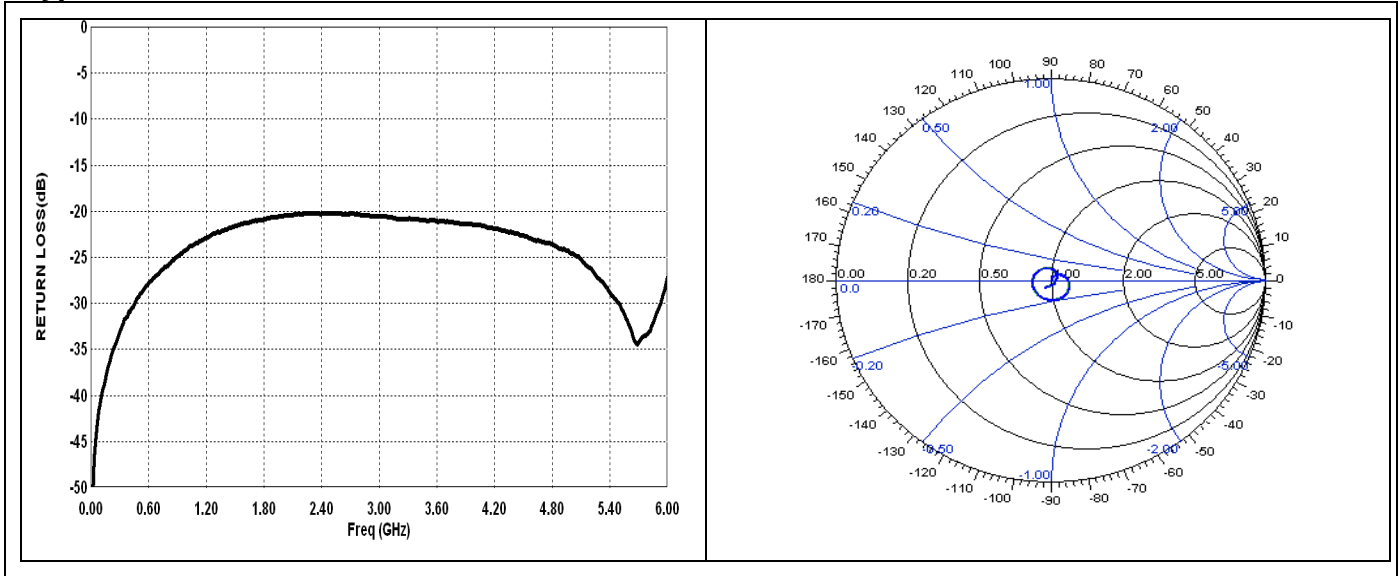


60-50TPR (097) Rev B



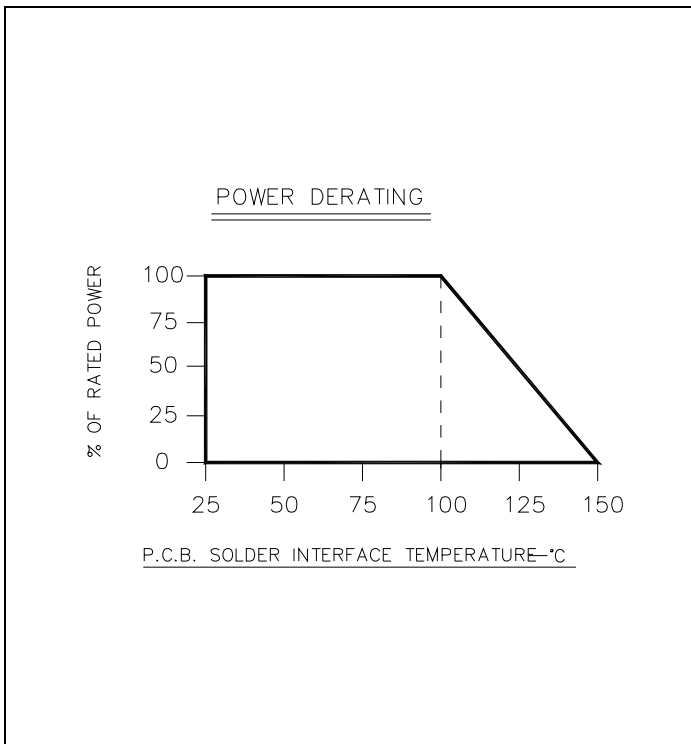


Typical Performance:



Power De-rating:

Mounting Footprint and Procedure:



Mounting Footprint and Procedure:

The diagrams show two methods for mounting the device on a PCB. The left method, labeled "SUGGESTED STRESS RELIEF METHODS", shows the device mounted on a board that is lower than the leads (left) and even with the leads (right). The right method, labeled "NOT RECOMMENDED APPLICATION", shows the device mounted on a board that is lower than the leads (left) and higher than the leads (right). A note indicates ".025 MIN. (2 PLACES)" for the lead height.

SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING APPROPRIATE SOLDER WITH A CONTROLLED TEMPERATURE IRON.

** FOR MORE DETAILS CONTACT FACTORY **

60-50TPR (097) Rev B

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Available on Tape and Reel For Pick and Place Manufacturing.



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